



SOT949-5

HVQFN56, thermal enhanced very thin quad flat package; no leads; 56 terminals; 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body

11 July 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Mounting method type	S (surface mount)
Issue date	05-06-2018
Manufacturer package code	98ASA01255D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	0.85	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	56	-	



2 Package outline

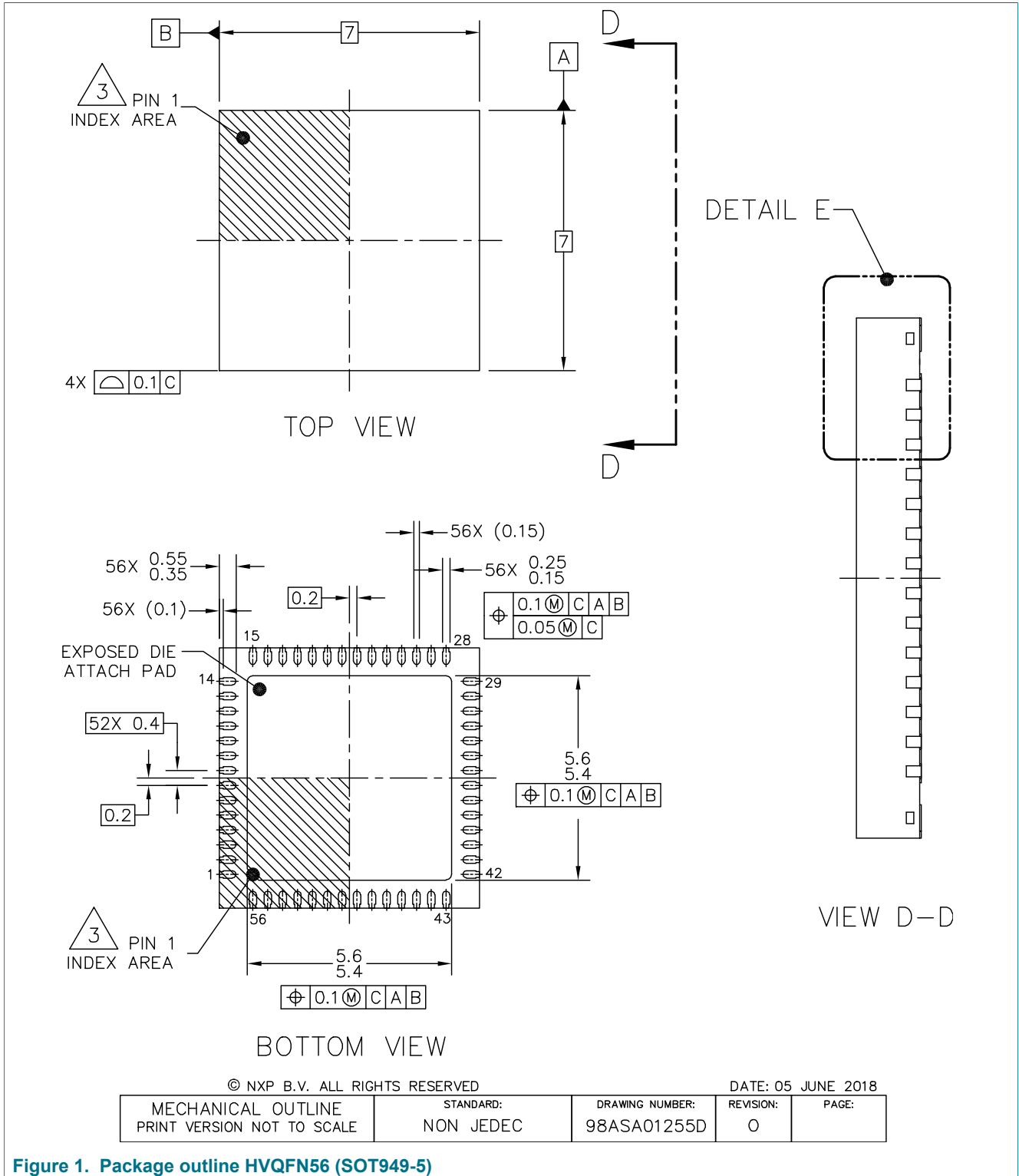


Figure 1. Package outline HVQFN56 (SOT949-5)

HVQFN56, thermal enhanced very thin quad flat package; no leads; 56 terminals; 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body

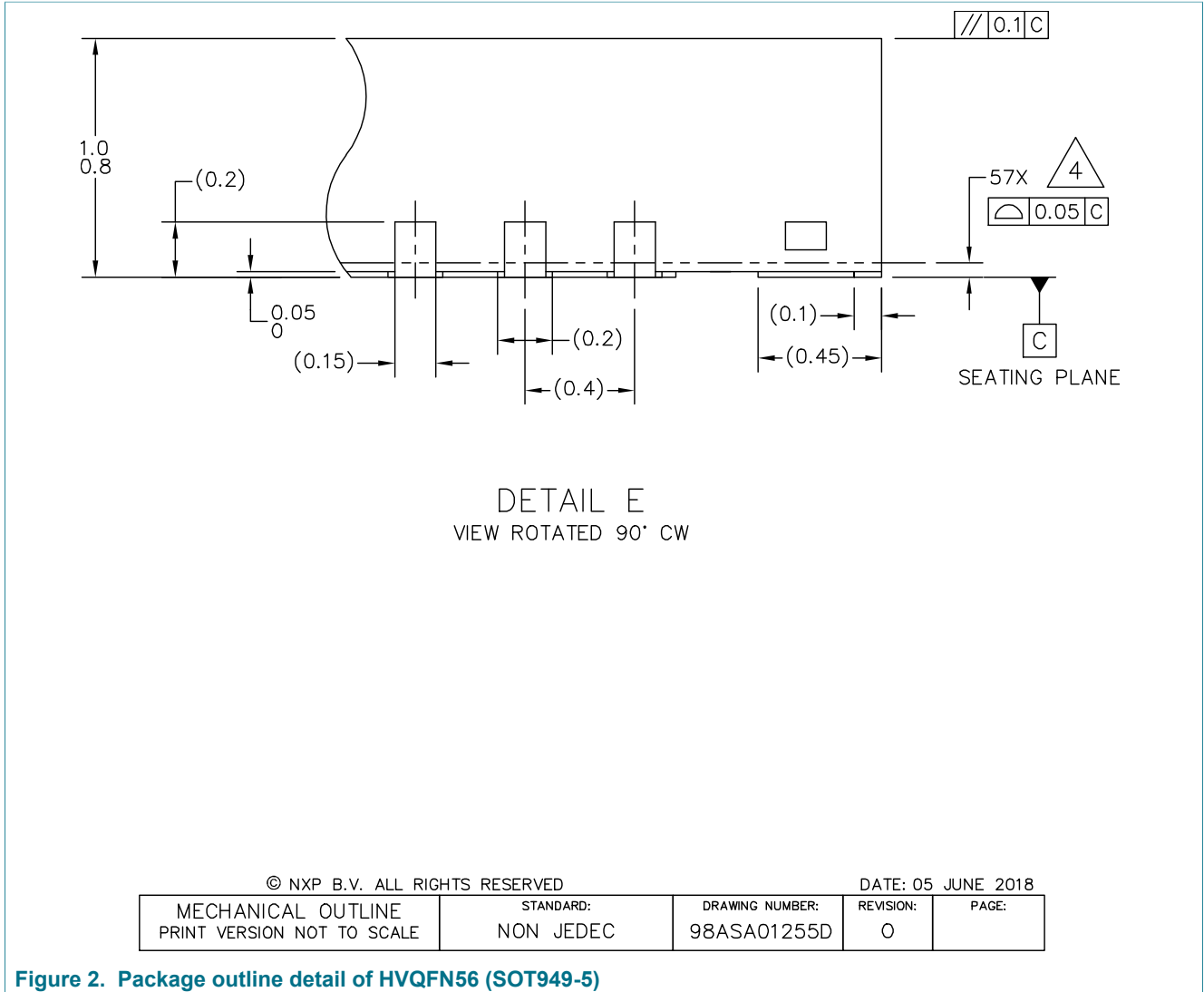




Figure 2. Package outline detail of HVQFN56 (SOT949-5)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3.  PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4.  COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP SHOULD BE 0.25 MM.

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Figure 3. Package outline note HVQFN56 (SOT949-5)

3 Soldering

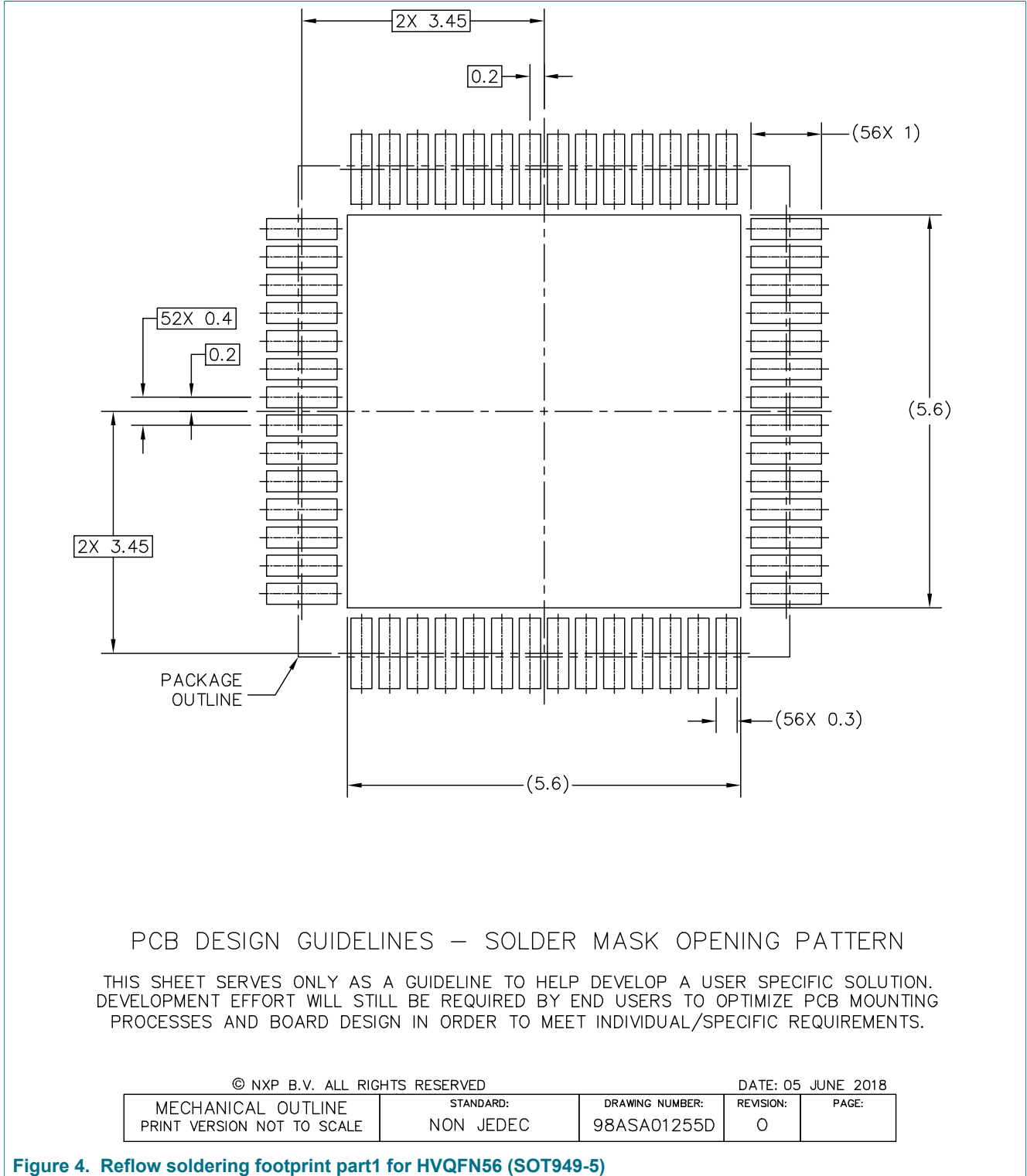
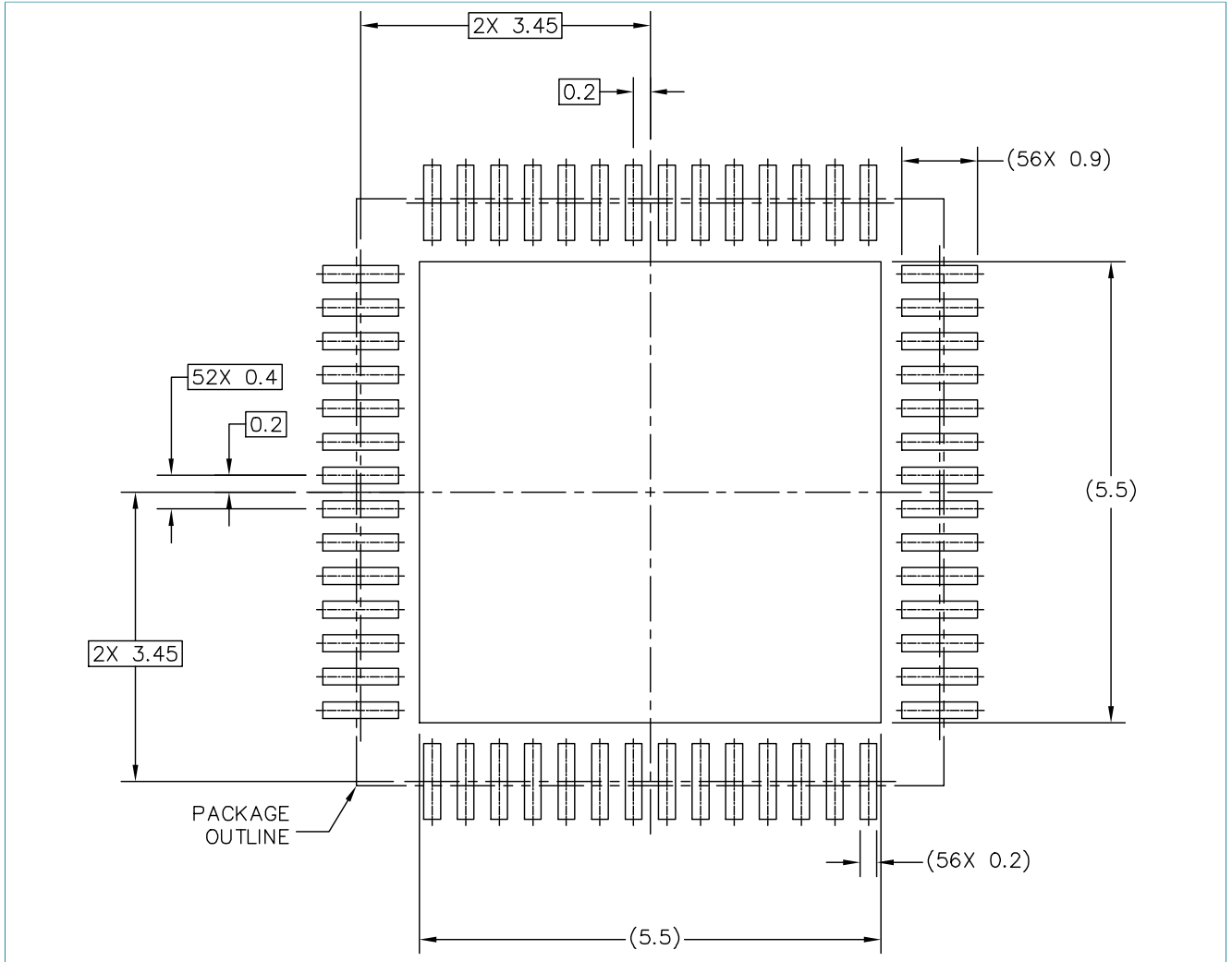


Figure 4. Reflow soldering footprint part1 for HVQFN56 (SOT949-5)

HVQFN56, thermal enhanced very thin quad flat package; no leads; 56 terminals; 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body



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Figure 5. Reflow soldering footprint part2 for HVQFN56 (SOT949-5)

HVQFN56, thermal enhanced very thin quad flat package; no leads; 56 terminals; 0.4 mm pitch, 7 mm x 7 mm x 0.85 mm body

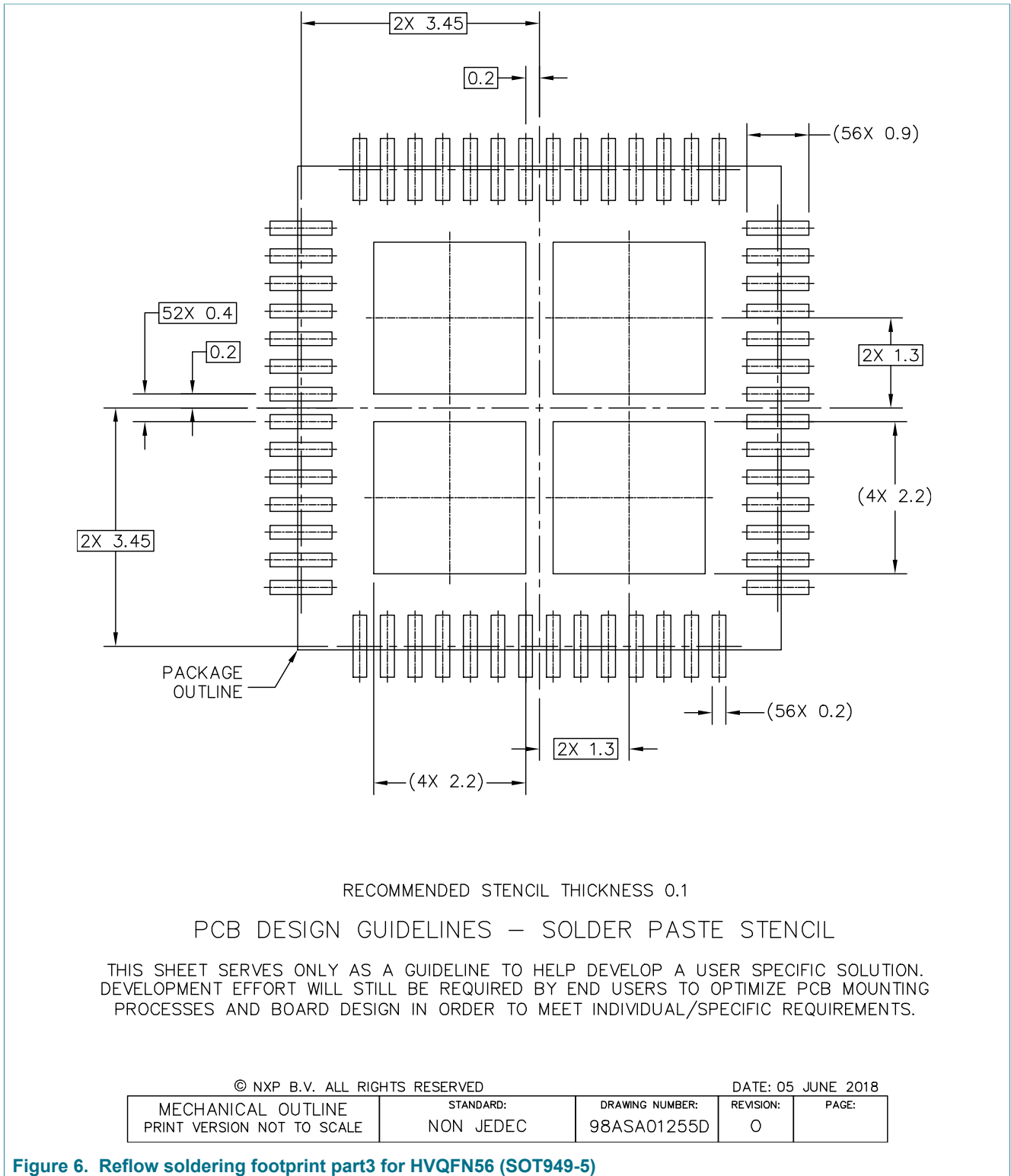


Figure 6. Reflow soldering footprint part3 for HVQFN56 (SOT949-5)

4 Legal information

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